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Itakura et al.

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(54) **SEMICONDUCTOR PACKAGE**

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(**) Term: **15 Years**

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(51) **LOC (12) Cl.** **13-03**

(52) **U.S. Cl.**
USPC **D13/182**

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361/679.01, 713, 728, 736, 760, 761, 772,
361/775, 783, 820; 174/250, 253;
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CPC . H01L 21/00; H01L 2224/42; H01L 2224/43;
H01L 2021/00; H01L 2021/02; H01L
2021/04; H01L 21/4814; H01L 21/4846;
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2924/171; H01L 2924/1711; H01L
2924/1715; H01L 2924/17151; H01L
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2924/1815; H01L 2924/19042; H01L
2924/1905; H01L 2224/08054; H01L

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G02B 6/4262; G02B 6/428; G02B
6/4281; H05K 1/14; H05K 1/141; H05K
1/142; H05K 1/144; H05K 1/18; H05K
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See application file for complete search history.

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PC

(57) **CLAIM**

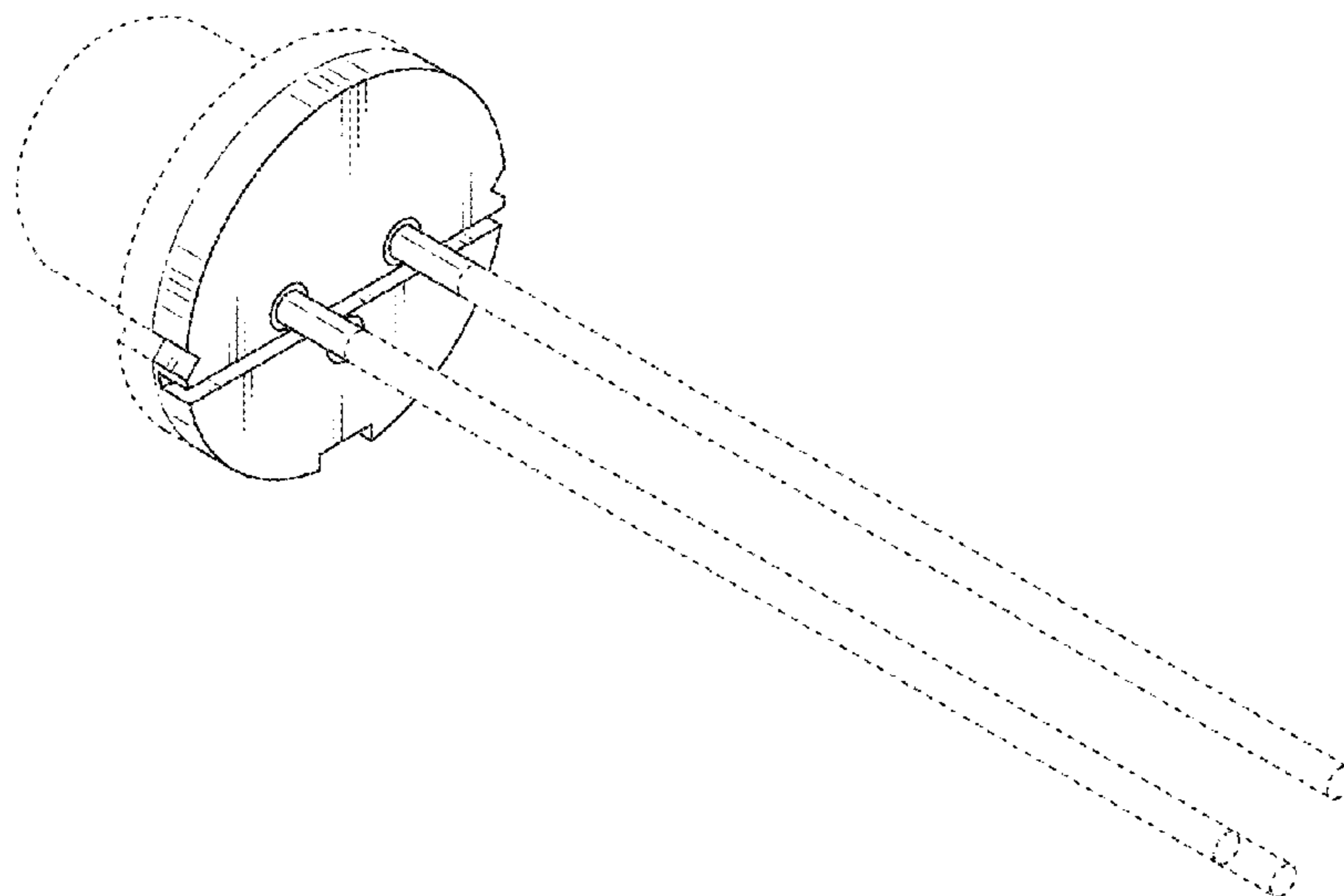
The ornamental design for a semiconductor package, as shown and described.

DESCRIPTION

FIG. 1 is a front, top and left side perspective view of a semiconductor package showing our new design;
FIG. 2 is a front view thereof;
FIG. 3 is a rear view thereof;
FIG. 4 is a top view thereof;
FIG. 5 is a bottom view thereof;
FIG. 6 is a left side view thereof; the right side view being a mirror image thereof;
FIG. 7 is a cross sectional view taken along line 7-7 of FIG. 2, with the internal system omitted; and,
FIG. 8 is another perspective view thereof, showing the state in use.

The parts shown in even dashed broken lines do not form part of the claimed design.

1 Claim, 5 Drawing Sheets



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Fig. 1

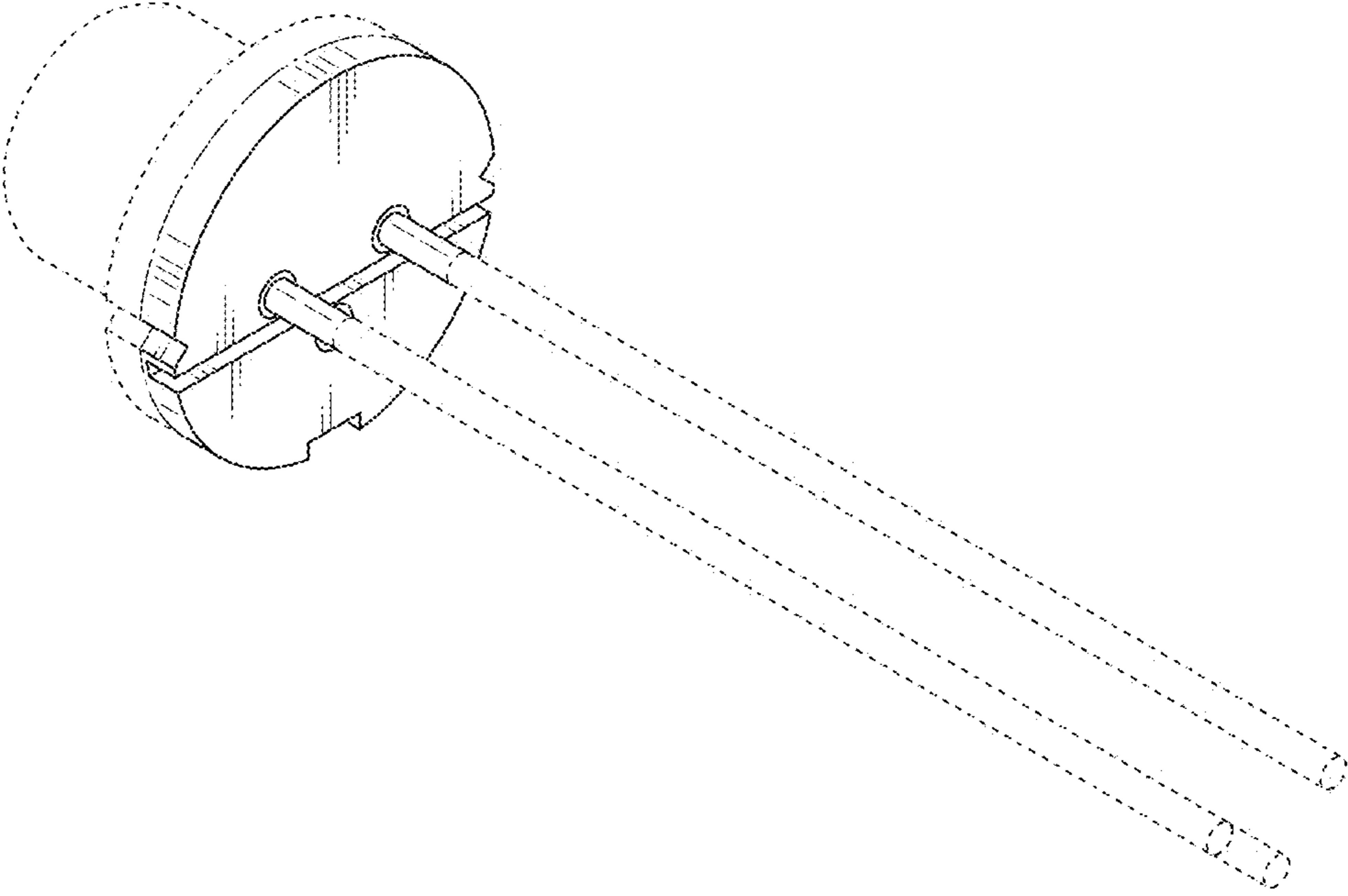


Fig. 2

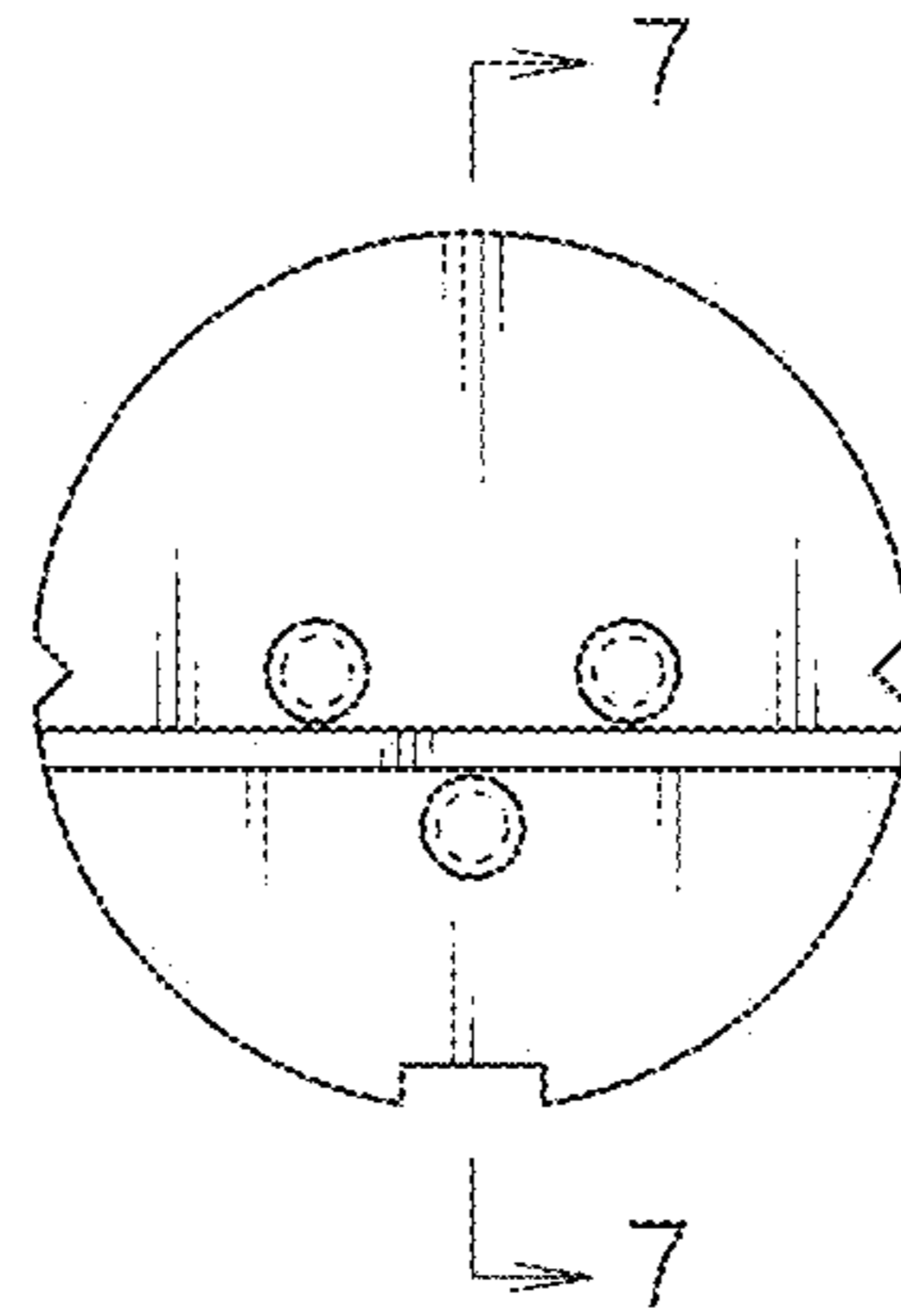


Fig. 3

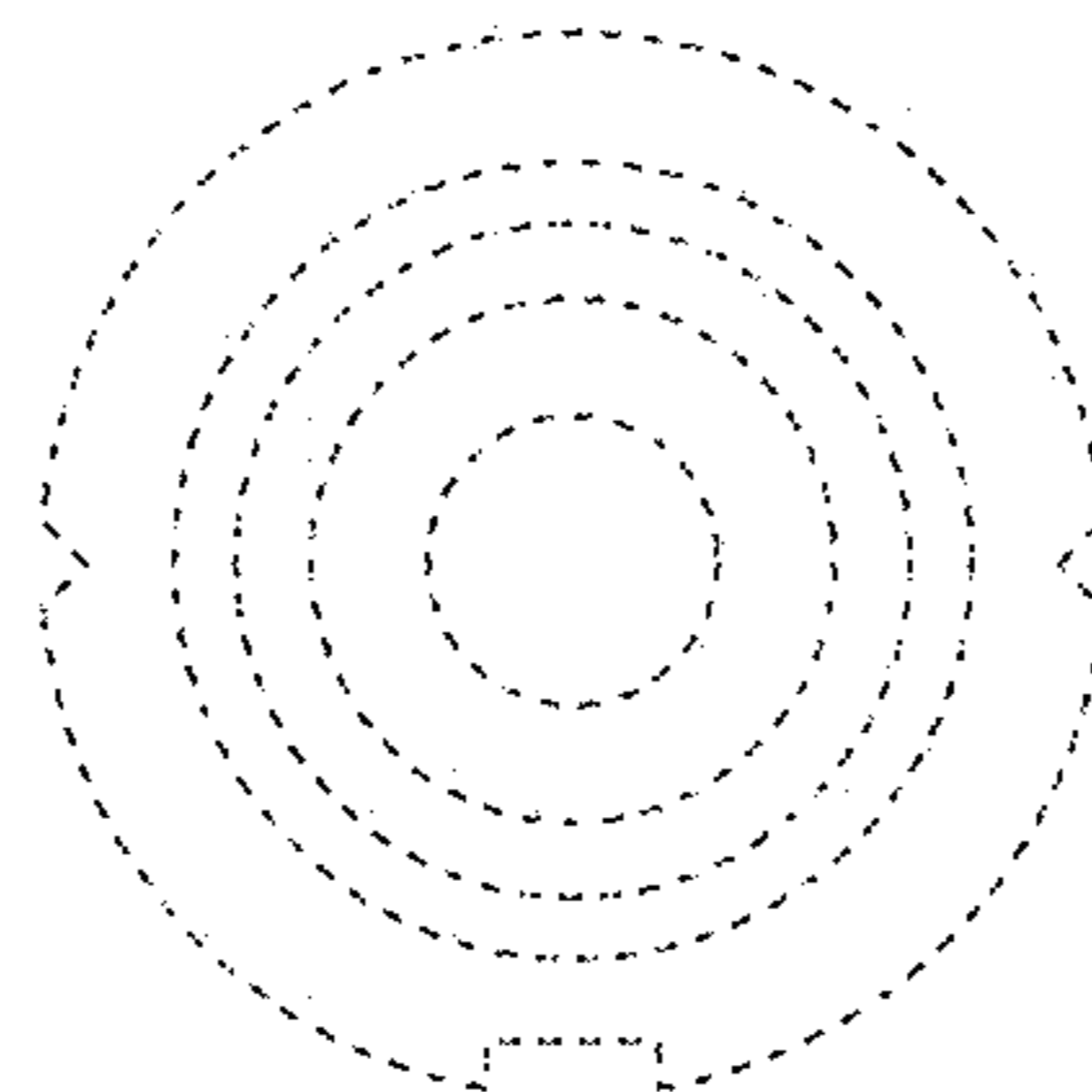


Fig. 4

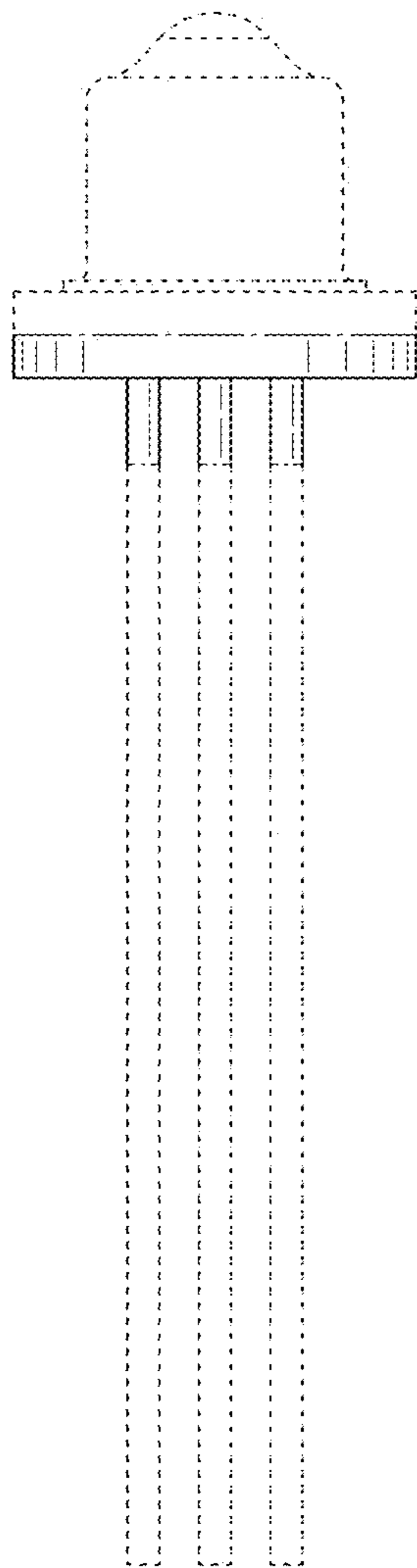


Fig. 5

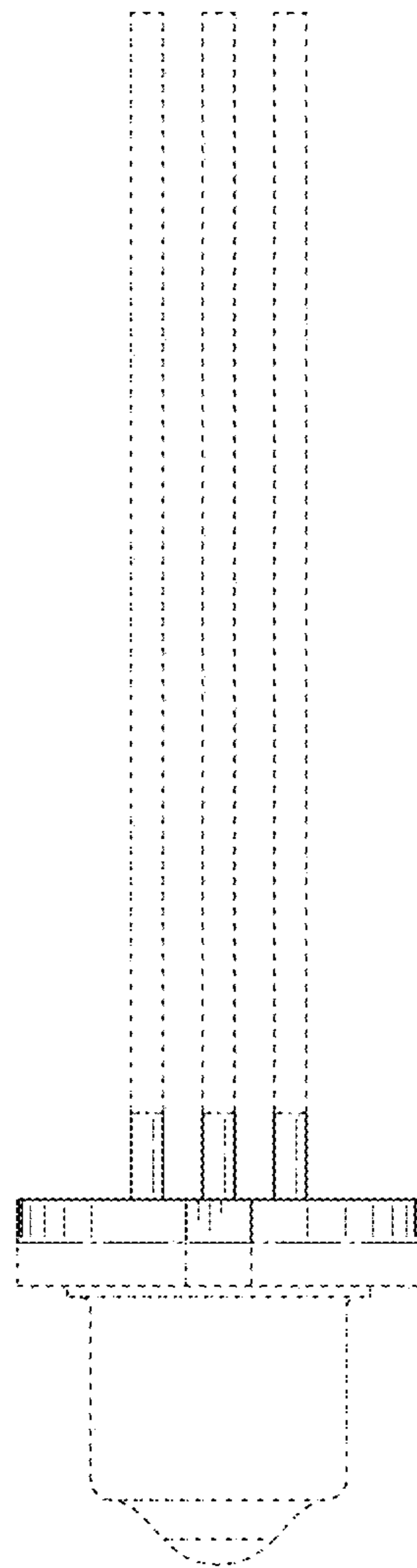


Fig. 6

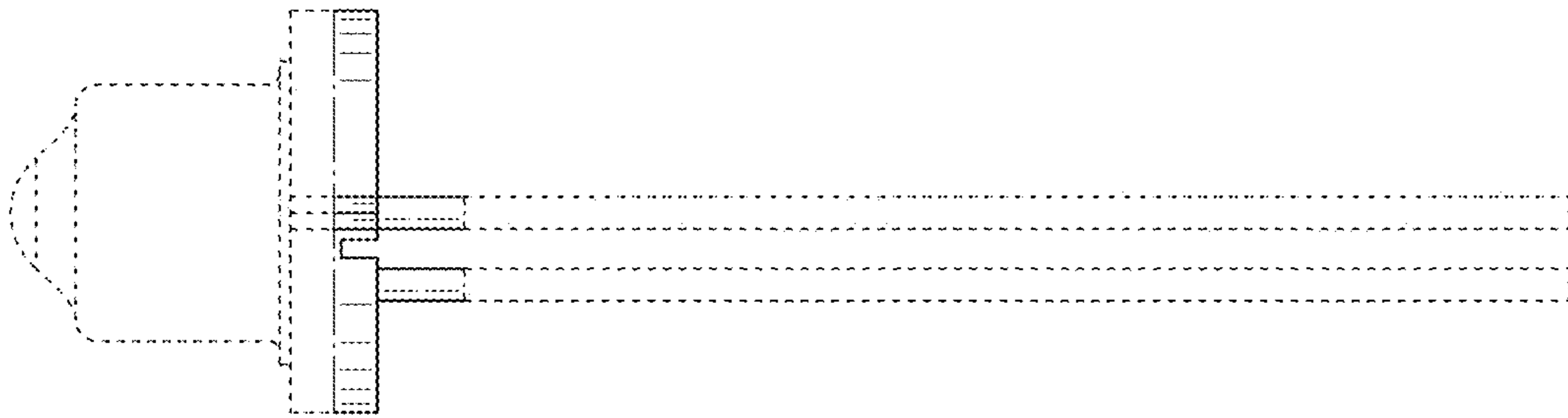


Fig. 7

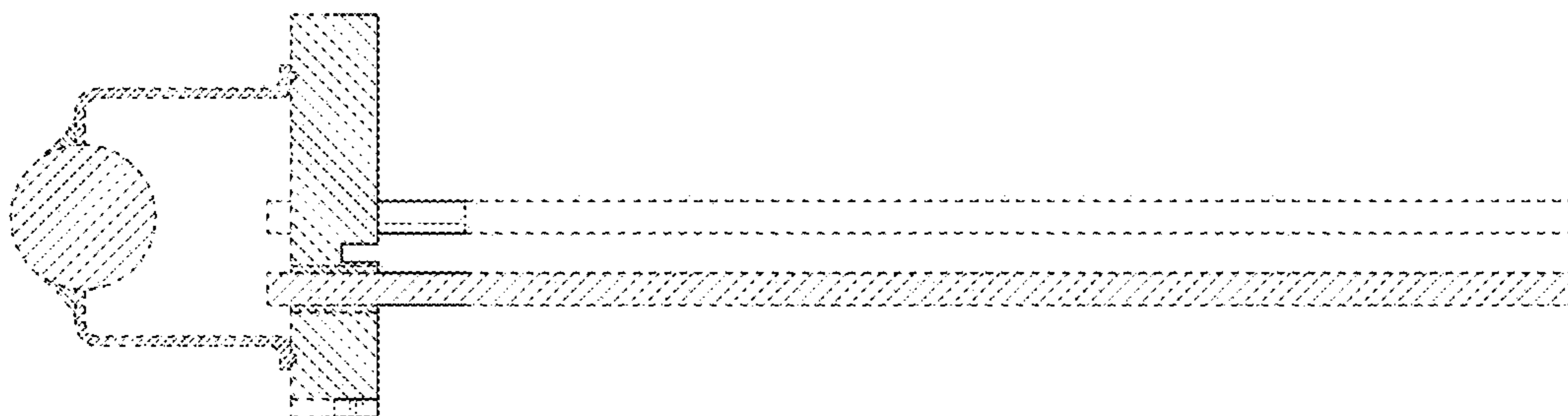


Fig. 8

